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#### (54) METHOD OF MANUFACTURING CIRCUIT **BOARD**

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#### (57)ABSTRACT

A method of manufacturing a circuit board is provided. The method includes forming an open substrate, in which the open substrate includes a substrate body having a top surface and a bottom surface; an opening in the substrate body, in which the opening has a first sidewall and a second sidewall opposite to the first sidewall; and at least one first fixing portion and at least one second fixing portion extending from the substrate body toward the opening, in which the first fixing portion and the second fixing portion are respectively protruded from the first sidewall and the second sidewall. A heat dissipation block is inserted in the opening to clamp the heat dissipation block between the first fixing portion and the second fixing portion, in which the heat dissipation block includes the heat dissipation block comprises a ceramic or a composite material.

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